

# P-Channel 100-V (D-S) MOSFET

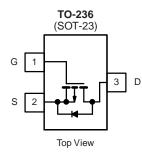
| PRODUCT SUMMARY     |                                   |                    |                       |  |  |  |
|---------------------|-----------------------------------|--------------------|-----------------------|--|--|--|
| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω)           | I <sub>D</sub> (A) | Q <sub>g</sub> (Typ.) |  |  |  |
| - 100               | 0.50 at V <sub>GS</sub> = - 10 V  | - 1.5              | 7.7                   |  |  |  |
|                     | 0.56 at V <sub>GS</sub> = - 6.0 V | - 1.4              | 1.1                   |  |  |  |

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21
  Available
- TrenchFET<sup>®</sup> Power MOSFET
- Ultra Low On-Resistance
- Small Size

#### **APPLICATIONS**

• Active Clamp Circuits in DC/DC Power Supplies



| ABSOLUTE MAXIMUM RATINGS $T_{\mu}$                                 | <sub>A</sub> = 25 °C, unle  | ss otherwise r                    | noted       |              |      |
|--|-----------------------------|-----------------------------------|-------------|--------------|------|
| Parameter  |                             | Symbol                            | 5 s         | Steady State | Unit |
| Drain-Source Voltage   |                             | V <sub>DS</sub>                   | - 100       |              | V    |
| Gate-Source Voltage  |                             | V <sub>GS</sub>                   | ± 20        |              |      |
| Continuous Drain Connect /T 450 °C\3 b                             | T <sub>A</sub> = 25 °C      | - I <sub>D</sub>                  | - 1.65      | - 1.5        |      |
| Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a, b</sup> | T <sub>A</sub> = 70 °C      |                                   | - 1.55      | - 1.4        |      |
| Pulsed Drain Current   |                             | I <sub>DM</sub>                   | - 3.0       |              | А    |
| Continuous Source Current (Diode Conduction) <sup>a, b</sup>       |                             | ۱ <sub>S</sub>                    | - 1.4       | - 1.0        |      |
| Single Pulse Avalanche Current                                     | gle Pulse Avalanche Current |                                   | 4.5         |              |      |
| Single Pulse Avalanche Energy                                      |                             | E <sub>AS</sub>                   | 1.01        |              | mJ   |
| Maria David Diastrational b  | T <sub>A</sub> = 25 °C      | - P <sub>D</sub>                  | 2.0         | 0.85         | W    |
| Maximum Power Dissipation <sup>a, b</sup>                          | T <sub>A</sub> = 70 °C      | 'D                                | 1.0         | 0.58         | vv   |
| Operating Junction and Storage Temperature Range                   |                             | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 150 |              | °C   |

| THERMAL RESISTANCE RATINGS               |              |                   |         |         |      |  |
|--|--------------|-------------------|---------|---------|------|--|
| Parameter                                |              | Symbol            | Typical | Maximum | Unit |  |
| Mauinum lunation to Ambienta             | t ≤ 5 s      | R <sub>thJA</sub> | 75      | 100     |      |  |
| Maximum Junction-to-Ambient <sup>a</sup> | Steady State | <b>1</b> thJA     | 120     | 166     | °C/W |  |
| Maximum Junction-to-Foot (Drain)         | Steady State | R <sub>thJF</sub> | 40      | 50      |      |  |

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. Pulse width limited by maximum junction temperature.

Available



|   |                      |   | Limits    |      |       |      |  |
|---|----------------------|---|-----------|------|-------|------|--|
| Parameter                               | Symbol               | Test Conditions   | Min.      | Тур. | Max.  | Unit |  |
| Static                                  |                      |   |           |      |       |      |  |
| Drain-Source Breakdown Voltage          | V <sub>(BR)DSS</sub> | $V_{GS} = 0 V, I_{D} = -250 \mu A$  | - 100     |      |       | V    |  |
| Gate-Threshold Voltage                  | V <sub>GS(th)</sub>  | $V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$   | - 1.0     |      | - 3.0 | v    |  |
| Gate-Body Leakage                       | I <sub>GSS</sub>     | $V_{DS} = 0 V, V_{GS} = \pm 20 V$   |           |      | ± 100 | nA   |  |
|   | 1                    | $V_{DS} = -100 \text{ V}, V_{GS} = 0 \text{ V}$   |           |      | - 1   | μΑ   |  |
| Zero Gate Voltage Drain Current         | IDSS                 | $V_{DS}$ = - 100 V, $V_{GS}$ = 0 V, $T_{J}$ = 55 °C   |           |      | - 10  |      |  |
| On-State Drain Current <sup>a</sup>     | I <sub>D(on)</sub>   | $V_{DS} \leq$ - 15 V, $V_{GS}$ = 10 V   | - 1.6     |      |       | А    |  |
| 2                                       | D                    | $V_{GS} = -10$ V, $I_{D} = -0.5$ A  | 0.50 0.56 |      | 0     |      |  |
| Drain-Source On-Resistance <sup>a</sup> | R <sub>DS(on)</sub>  | V <sub>GS</sub> = - 6.0 V, I <sub>D</sub> = - 0.5 A   |           |      |       | Ω    |  |
| Forward Transconductance <sup>a</sup>   | 9 <sub>fs</sub>      | $V_{DS}$ = - 15 V, $I_{D}$ = - 0.5 A  |           | 2.2  |       | S    |  |
| Diode Forward Voltage                   | V <sub>SD</sub>      | I <sub>S</sub> = - 1.0 A, V <sub>GS</sub> = 0 V   |           | 0.7  | - 1.2 | V    |  |
| Dynamic <sup>b</sup>                    |                      |   | •         |      |       |      |  |
| Total Gate Charge                       | Qg                   |   |           | 7.7  | 12    |      |  |
| Gate-Source Charge                      | Q <sub>gs</sub>      | $V_{DS} = -50 \text{ V}, V_{GS} = 10 \text{ V},$<br>$I_{D} \cong -0.5 \text{ A}$                |           | 1.5  |       | nC   |  |
| Gate-Drain Charge                       | Q <sub>gd</sub>      | 1 <u>D</u> = - 0.0 A  |           | 2.5  |       |      |  |
| Gate Resistance                         | Rg                   | f = 1.0 MHz   |           | 9    |       | Ω    |  |
| Input Capacitance                       | C <sub>iss</sub>     |   |           | 520  |       |      |  |
| Output Capacitance                      | C <sub>oss</sub>     | $V_{DS}$ = - 25 V, $V_{GS}$ = 0 V, f = 1 MHz  |           | 40   |       | pF   |  |
| Reverse Transfer Capacitance            | C <sub>rss</sub>     |   |           | 20   |       | 1    |  |
| Switching <sup>c</sup>                  |                      |   | •         |      |       |      |  |
|   | t <sub>d(on)</sub>   |   |           | 7    | 11    |      |  |
| Turn-On Time                            | t <sub>r</sub>       | $V_{DD}$ = - 50 V, R <sub>L</sub> = 75 Ω<br>I <sub>D</sub> ≅ - 1.0 A, V <sub>GEN</sub> = - 10 V |           | 11   | 17    | - ns |  |
| Turn Off Time                           | t <sub>d(off)</sub>  | $R_{\rm g} = 6 \Omega$  |           | 16   | 25    |      |  |
| Turn-Off Time                           | t <sub>f</sub>       | g = 0 22  |           | 11   | 17    |      |  |
| Body Diode Reverse Recovery Charge      | Q <sub>rr</sub>      | I <sub>F</sub> = 0.5 A, dl/dt = 100 A/µs  |           | 90   | 135   | nC   |  |

Notes:

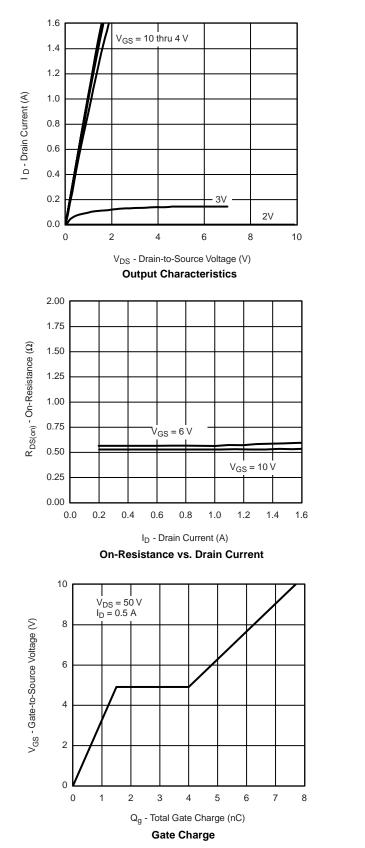
a. Pulse test: PW  $\leq$  300  $\mu s$  duty cycle  $\leq$  2 %.

b. For DESIGN AID ONLY, not subject to production testing.

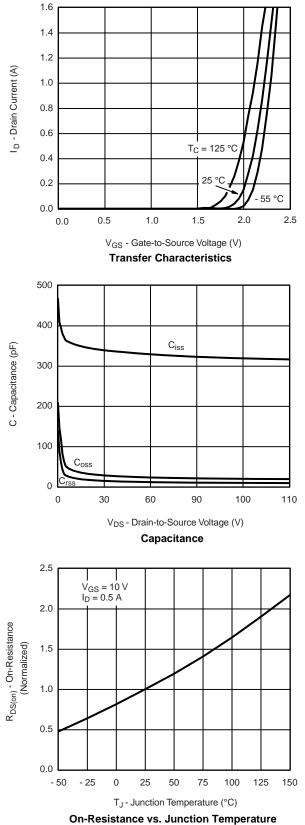
c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

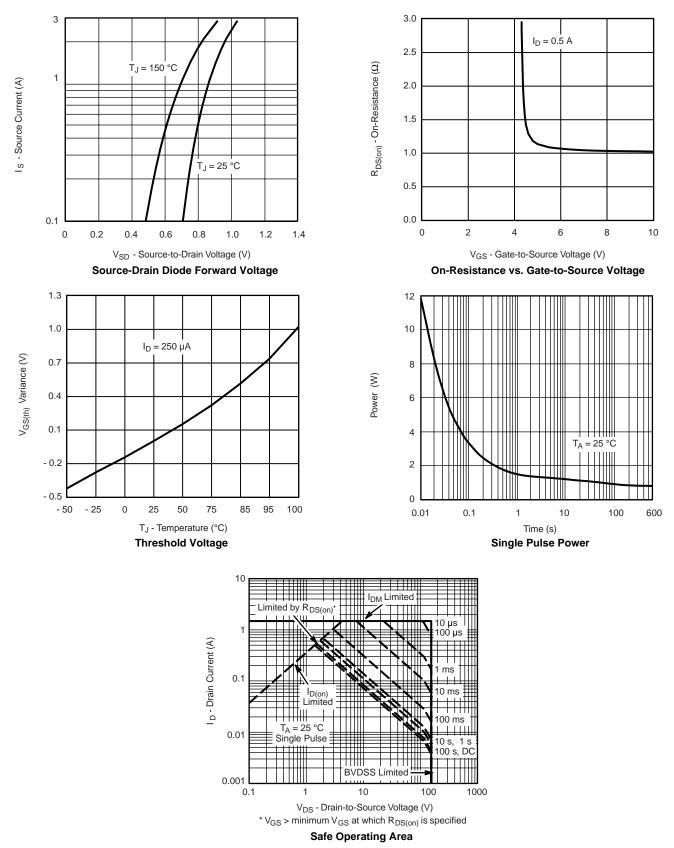




#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

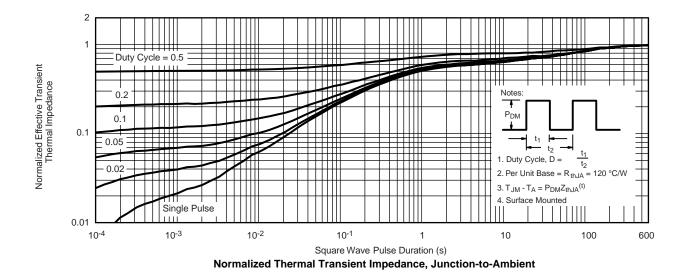






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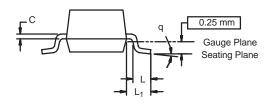
#### THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



## SOT-23 (TO-236): 3-LEAD







| Dim            | MILLIM   | IETERS | INCHES     |         |  |  |
|----------------|----------|--------|------------|---------|--|--|
|                | Min      | Max    | Min        | Max     |  |  |
| Α              | 0.89     | 1.12   | 0.035      | 0.044   |  |  |
| A <sub>1</sub> | 0.01     | 0.10   | 0.0004     | 0.004   |  |  |
| A <sub>2</sub> | 0.88     | 1.02   | 0.0346     | 0.040   |  |  |
| b              | 0.35     | 0.50   | 0.014      | 0.020   |  |  |
| C              | 0.085    | 0.18   | 0.003      | 0.007   |  |  |
| D              | 2.80     | 3.04   | 0.110      | 0.120   |  |  |
| E              | 2.10     | 2.64   | 0.083      | 0.104   |  |  |
| E <sub>1</sub> | 1.20     | 1.40   | 0.047      | 0.055   |  |  |
| е              | 0.95 BSC |        | 0.0374 Ref |         |  |  |
| e <sub>1</sub> | 1.90 BSC |        | 0.074      | 748 Ref |  |  |
| L              | 0.40     | 0.60   | 0.016      | 0.024   |  |  |
| L <sub>1</sub> | 0.64 Ref |        | 0.025      | 5 Ref   |  |  |
| S              | 0.50 Ref |        | 0.020      | ) Ref   |  |  |
| q              | 3°       | 8°     | 3°         | 8°      |  |  |



### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)



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